Amendments to Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (currently amended) A cooling system for a heat emitting device, the cooling system operating using a fluid having a liquid phase, the cooling system comprising:

a substrate including at least a portion of microchannel disposed therein, the substrate adapted to physically connect to the heat emitting device, thereby providing for the transfer of thermal energy from the heat emitting device to the substrate, and the further transfer of thermal energy from the substrate to the fluid disposed within the microchannel, the microchannel configured to provide flow of the fluid therethrough;

a heat exchanger configured to provide flow of the fluid therethrough and the transfer of thermal energy out of the fluid;

a high flow rate electroosmotic pump, the electroosmotic pump creating the flow of the fluid and managing a plurality of generated gases; and

wherein the substrate, the heat exchanger, and the electroosmotic pump are configured to operate together to create a closed loop fluid flow.

2.-114. (canceled)

115. (currently amended) A heat exchanger connected to a heat-generating device including a plurality of regions of varying heat densities in a cooling system wherein the heat exchanger operates using a fluid having a liquid phase, comprising:

a substrate fabricated from a material selected for its thermal conduction capability and adapted to connect to the heat-generating device; and

a microchannel disposed in the substrate for transfer of thermal energy to the fluid as the fluid is pumped through the heat exchanger wherein the arrangement of the microchannel is selected to minimize the temperature differences across the heat-generating device.

116. (previously presented) The heat exchanger connected to a heat-generating device of claim 115 wherein the substrate material is selected based on an approximate matching of a thermal expansion coefficient of the heat-generating device to which the heat exchanger is connected.

117. (previously presented) The heat exchanger connected to a heat-generating device of claim 115 wherein the substrate material is selected from a plurality of thin metal sheets, or a silicon layer and a glass layer, or a ceramic, or a carbon-fiber composite.

118. (previously presented) The heat exchanger connected to a heat-generating device of claim 115 wherein the substrate comprises a plurality of layers.

119. (previously presented) The heat exchanger connected to a heat-generating device of claim 118 wherein the plurality of layers comprise different materials.

120. (previously presented) The heat exchanger connected to a heat-generating device of claim 115 wherein the substrate is connected to a surface of the heat-generating device by a thermal attach material.

121. (previously presented) The heat exchanger connected to a heat-generating device of claim 120 wherein the thermal attach material is a silver-filled epoxy or solder.

122. (previously presented) The heat exchanger connected to a heat-generating device of claim 115 wherein the substrate and the heat-generating device are fabricated from silicon.

123. (previously presented) The heat exchanger connected to a heat-generating device of claim 115 wherein the heat-generating device is fabricated from silicon and the substrate is fabricated from a metal.

124. (previously presented) The heat exchanger connected to a heat-generating device of claim 115 wherein the substrate further comprises a thermometer integrated into the heat exchanger for providing a feedback signal to a controller in response to a local change in temperature to enable dynamic temperature control within the substrate.

125. (previously presented) The heat exchanger connected to a heat-generating device of claim 115 wherein the substrate comprises at least two layers and the microchannel is confined to a single layer.

126. (previously presented) The heat exchanger connected to a heat-generating device of claim 115 wherein the substrate comprises at least two layers and the microchannel is formed in more than one layer.

127. (previously presented) The heat exchanger connected to a heat-generating device of claim 125 wherein the at least two layers are fabricated from silicon and glass and are bonded by any one of the following bonding processes: anodic, fusion, eutectic and adhesive.

128. (previously presented) The heat exchanger connected to a heat-generating device of claim 125 wherein the at least two layers are fabricated from metal and are bonded by any one of the following: welding, soldering, eutectic bonding and adhesive bonding.

129. (previously presented) The heat exchanger connected to a heat-generating device of claim 115 further comprising a high flow rate electroosmotic pump integrated into the substrate for pumping fluid through the heat exchanger.

130. (previously presented) The heat exchanger connected to a heat-generating device of claim 129 further comprising a microcontroller integrated into the substrate for monitoring a plurality of temperature, pressure and flow rate sensors disposed in the heat exchanger and providing a driving voltage to a power supply associated with the high flow rate electroosmotic pump.

131. (previously presented) The heat exchanger connected to a heat-generating device of claim 118 wherein the microchannel is disposed in the layer of the substrate that is in direct contact with the heat-generating device.

132. (previously presented) The heat exchanger connected to a heat-generating device of claim 118 wherein the plurality of layers comprise a bottom layer, at least one middle layer and

a top layer, and each of the bottom, middle and top layers may be fabricated from a different material.

133. (previously presented) The heat exchanger connected to a heat-generating device of claim 132 wherein the bottom layer is fabricated from a metal, or silicon, or glass, or a ceramic, or a plastic.

134. (previously presented) The heat exchanger connected to a heat-generating device of claim 133 wherein the bottom layer is fabricated from copper.

135. (previously presented) The heat exchanger connected to a heat-generating device of claim 133 wherein the bottom layer is fabricated from Kovar.

136. (previously presented) The heat exchanger connected to a heat-generating device of claim 132 wherein the at least one middle layer is fabricated from silicon.

137. (previously presented) The heat exchanger connected to a heat-generating device of claim 132 wherein the at least one middle layer is fabricated from a metal.

138. (previously presented) The heat exchanger connected to a heat-generating device of claim 132 wherein the top layer is fabricated from a glass or a plastic.

139. (canceled)

140. (currently amended) A heat exchanger connected to a heat-generating device in a cooling system wherein the heat exchanger operates using a fluid having a liquid phase, comprising:

a substrate fabricated from a material selected for its thermal conduction capability and adapted to connect to the heat-generating device;

a high flow rate electroosmotic pump integrated into the substrate for pumping fluid through the heat exchanger <u>and managing a plurality of generated gases;</u> and

a microchannel disposed in the substrate for transfer of thermal energy to the fluid as the fluid is pumped through the heat exchanger wherein at least one inlet and at least one outlet are positioned on a side of the heat exchanger.

141. (previously presented) The heat exchanger connected to a heat-generating device of claim 140 wherein the substrate material is selected based on an approximate matching of a

thermal expansion coefficient of the heat-generating device to which the heat exchanger is connected.

142. (previously presented) The heat exchanger connected to a heat-generating device of claim 140 wherein the substrate material is selected from a plurality of thin metal sheets, or a silicon layer and a glass layer, or a ceramic, or a carbon-fiber composite.

143. (previously presented) The heat exchanger connected to a heat-generating device of claim 140 wherein the substrate comprises a plurality of layers.

144. (previously presented) The heat exchanger connected to a heat-generating device of claim 143 wherein the plurality of layers comprise different materials.

145. (previously presented) The heat exchanger connected to a heat-generating device of claim 140 wherein the substrate is connected to a surface of the heat-generating device by a thermal attach material.

146. (previously presented) The heat exchanger connected to a heat-generating device of claim 145 wherein the thermal attach material is a silver-filled epoxy or solder.

147. (previously presented) The heat exchanger connected to a heat-generating device of claim 140 wherein the substrate and the heat-generating device are fabricated from silicon.

148. (previously presented) The heat exchanger connected to a heat-generating device of claim 140 wherein the heat-generating device is fabricated from silicon and the substrate is fabricated from a metal.

149. (previously presented) The heat exchanger connected to a heat-generating device of claim 140 wherein the substrate further comprises a thermometer integrated into the heat exchanger for providing a feedback signal to a controller in response to a local change in temperature to enable dynamic temperature control within the substrate.

150. (previously presented) The heat exchanger connected to a heat-generating device of claim 140 wherein the substrate comprises at least two layers and the microchannel is confined to a single layer.

151. (previously presented) The heat exchanger connected to a heat-generating device of claim 150 wherein the substrate comprises at least two layers and the microchannel is formed in more than one layer.

152. (previously presented) The heat exchanger connected to a heat-generating device of claim 150 wherein the at least two layers are fabricated from silicon and glass and are bonded by any one of the following bonding processes: anodic, fusion, eutectic and adhesive.

153. (previously presented) The heat exchanger connected to a heat-generating device of claim 150 wherein the at least two layers are fabricated from metal and are bonded by any one of the following: welding, soldering, eutectic bonding and adhesive bonding.

154. (canceled)

155. (previously presented) The heat exchanger connected to a heat-generating device of claim 140 further comprising a microcontroller integrated into the substrate for monitoring a plurality of temperature, pressure and flow rate sensors disposed in the heat exchanger and providing a driving voltage to a power supply associated with the high flow rate electroosmotic pump.

156. (previously presented) The heat exchanger connected to a heat-generating device of claim 143 wherein the microchannel is disposed in the layer of the substrate that is in direct contact with the heat-generating device.

157. (previously presented) The heat exchanger connected to a heat-generating device of claim 143 wherein the plurality of layers comprise a bottom layer, at least one middle layer and a top layer, and each of the bottom, middle and top layers may be fabricated from a different material.

158. (previously presented) The heat exchanger connected to a heat-generating device of claim 157 wherein the bottom layer is fabricated from a metal, or silicon, or glass, or a ceramic, or a plastic.

159. (previously presented) The heat exchanger connected to a heat-generating device of claim 158 wherein the bottom layer is fabricated from copper.

160. (previously presented) The heat exchanger connected to a heat-generating device of claim 158 wherein the bottom layer is fabricated from Kovar.

161. (previously presented) The heat exchanger connected to a heat-generating device of claim 157 wherein the at least one middle layer is fabricated from silicon.

162. (previously presented) The heat exchanger connected to a heat-generating device of claim 157 wherein the at least one middle layer is fabricated from a metal.

163. (previously presented) The heat exchanger connected to a heat-generating device of claim 157 wherein the top layer is fabricated from a glass or a plastic.

164. (currently amended) A heat exchanger for the transfer of heat from a heat-generating device including a plurality of regions of varying heat densities in a cooling system wherein the heat exchanger operates using a fluid having a liquid phase, comprising:

a multi-layer substrate fabricated from a plurality of materials that are bonded together and attached to the heat-generating device; and

a microchannel disposed in at least one layer of the substrate for transfer of thermal energy to the fluid as the fluid is pumped through the heat exchanger wherein the arrangement of the microchannel is selected to minimize the temperature differences across the heat-generating device.

165. (canceled)

166. (previously presented) A heat exchanger for the transfer of heat from a heat-generating device including a plurality of regions of varying heat densities in a cooling system wherein the heat exchanger operates using a fluid having a liquid phase, comprising:

a multi-layer substrate fabricated from a plurality of materials that are bonded together and attached to the heat-generating device; and

a microchannel disposed in at least one layer of the substrate for transfer of thermal energy to the fluid as the fluid is pumped through the heat exchanger by a high flow rate fluid pump and wherein at least one inlet and at least one outlet are positioned on a side of the heat exchanger.

167. (currently amended) A cooling system for a heat emitting device including a plurality of regions of varying heat densities, the cooling system operating using a fluid having a liquid phase, the cooling system comprising:

a substrate including at least a portion of a microchannel disposed therein, the substrate adapted to physically connect to the heat emitting device, thereby providing for the transfer of thermal energy from the heat emitting device to the substrate, and the further transfer of thermal energy from the substrate to the fluid disposed within the microchannel, the microchannel configured to provide flow of the fluid therethrough and wherein the arrangement of the microchannel is selected to minimize the temperature differences across the heat emitting device;

a heat exchanger configured to provide flow of the fluid therethrough and the transfer of thermal energy out of the fluid;

a high flow rate fluid pump for creating the flow of the fluid; and

wherein the substrate, the heat exchanger, and the fluid pump are configured to operate together to create a closed loop fluid flow.

168. (previously presented) The cooling system according to claim 167 wherein the fluid pump is disposed between the heat exchanger and the substrate such that the fluid is pumped into the microchannel of the substrate from the fluid pump.

169. (previously presented) The cooling system according to claim 167 wherein the microchannel includes a plurality of parallel subchannels, each of the parallel subchannels sharing a common inlet portion and a common outlet portion.

170. (previously presented) The cooling system according to claim 169 further including a temperature sensor disposed in proximity to the plurality of parallel subchannels.

171. (previously presented) The cooling system according to claim 170 further including a temperature control circuit that receives as inputs signals from the temperature sensor.

172. (previously presented) The cooling system according to claim 167 wherein the substrate is comprised of a plurality of layers, and wherein at least a portion of the microchannel is formed within both a first and a second layer.

173. (previously presented) The cooling system according to claim 167 wherein the substrate is comprised of a first layer and a second layer, the first layer being physically connected to the heat emitting device, and wherein at least a portion of the microchannel is formed within only the first layer.

174. (previously presented) The cooling system according to claim 167 wherein the heat emitting device is comprised of a plurality of integrated circuits and the substrate is disposed between the plurality of integrated circuits.

175. (previously presented) The cooling system according to claim 167 wherein the heat emitting device includes a plurality of regions with several regions having a higher heat density than other regions.

176. (previously presented) The cooling system according to claim 167 wherein the substrate further includes a plurality of vertical electrical interconnects.

177. (previously presented) The cooling system according to claim 176 wherein the microchannel further includes vertical and horizontal fluid channels.

178. (previously presented) The cooling system according to claim 176 wherein the plurality of vertical interconnects provide a portion of an electrical connection that electrically connects a plurality of temperature sensors to a temperature control circuit.

179. (previously presented) The cooling system according to claim 167 wherein the substrate includes an opening through which another interaction is capable of impinging upon a portion of the heat emitting device.

180. (previously presented) The cooling system according to claim 179 wherein the another interaction is an electrical interaction.

181. (previously presented) The cooling system according to claim 179 wherein the another interaction is an electrical connection to a surface of the device to which the substrate is physically connected, and which electrical connection does not pass through any portion of the substrate.

182. (previously presented) The cooling system according to claim 179 wherein the another interaction is one of pressure, sound, chemical, mechanical force, and an electromagnetic field.

183. (previously presented) The cooling system according to claim 179 wherein the opening is created by a surface area of the substrate that contacts a corresponding surface area of the device being smaller than the corresponding surface area of the device.

184. (previously presented) The cooling system according to claim 167 wherein a portion of the microchannel includes:

an upper chamber;

a lower chamber; and

a plurality of subchannels disposed between the upper chamber and the lower chamber wherein the arrangement of the subchannels is selected to minimize the temperature differences across the heat emitting device.

185. (previously presented) The cooling system according to claim 167 further including a pressure sensor.

186. (previously presented) The cooling system according to claim 167 further including a temperature sensor disposed within the substrate.

187. (previously presented) The cooling system according to claim 186 further including a temperature control circuit that receives as inputs signals from the temperature sensor.

188. (previously presented) The cooling system according to claim 167 further including a temperature sensor disposed in the loop at a location other than within the substrate.

189. (previously presented) The cooling system according to claim 167 wherein the microchannel includes a portion containing a partial blocking structure to increase surface area contacting the fluid.

190. (previously presented) The cooling system according to claim 189 wherein the partial blocking structure is comprised of a roughened portion of a microchannel wall.

191. (previously presented) The cooling system according to claim 189 wherein the partial blocking structure is disposed within the microchannel.

192. (previously presented) The cooling system according to claim 167 wherein the heat emitting device includes a plurality of regions with several regions having a higher heat density than other regions.

193. (currently amended) A cooling system for a heat emitting device <u>including a plurality of regions of varying heat densities</u>, the cooling system operating using a fluid having a liquid phase, the cooling system comprising:

a substrate including at least a portion of a microchannel disposed therein, the substrate adapted to physically connect to the heat emitting device, thereby providing for the transfer of thermal energy from the heat emitting device to the substrate, and the further transfer of thermal energy from the substrate to the fluid disposed within the microchannel, the microchannel configured to provide flow of the fluid therethrough;

a heat exchanger configured to provide for (i) the flow of the fluid therethrough, wherein at least one inlet and at least one outlet are positioned on a side of the heat exchanger, and (ii) the transfer of thermal energy out of the fluid;

a high flow rate fluid pump for creating the flow of the fluid ; and

wherein the substrate, the heat exchanger, and the fluid pump are configured to operate together to create a closed loop fluid flow.

194. (previously presented) The cooling system according to claim 193 wherein the high flow rate fluid pump is disposed between the heat exchanger and the substrate such that the fluid is pumped into the microchannel of the substrate from the fluid pump.

195. (previously presented) The cooling system according to claim 193 wherein the microchannel includes a plurality of parallel subchannels, each of the parallel subchannels sharing a common inlet portion and a common outlet portion.

196. (previously presented) The cooling system according to claim 195 further including a temperature sensor disposed in proximity to the plurality of parallel subchannels.

197. (previously presented) The cooling system according to claim 196 further including a temperature control circuit that receives as inputs signals from the temperature sensor.

198. (previously presented) The cooling system according to claim 193 wherein the substrate is comprised of a plurality of layers, and wherein at least a portion of the microchannel is formed within both a first and a second layer.

199. (previously presented) The cooling system according to claim 193 wherein the substrate is comprised of a first layer and a second layer, the first layer being physically connected

to the heat emitting device, and wherein at least a portion of the microchannel is formed within only the first layer.

200. (previously presented) The cooling system according to claim 193 wherein the heat emitting device is comprised of a plurality of integrated circuits and the substrate is disposed between the plurality of integrated circuits.

201. (previously presented) The cooling system according to claim 193 wherein the substrate further includes a plurality of vertical electrical interconnects.

202. (previously presented) The cooling system according to claim 201 wherein the microchannel further includes vertical and horizontal fluid channels.

203. (previously presented) The cooling system according to claim 201 wherein the plurality of vertical interconnects provide a portion of an electrical connection that electrically connects a plurality of temperature sensors to a temperature control circuit.

204. (previously presented) The cooling system according to claim 193 wherein the substrate includes an opening through which another interaction is capable of impinging upon a portion of the heat emitting device.

205. (previously presented) The cooling system of claim 204 wherein the another interaction is an electrical interaction.

206. (previously presented) The cooling system according to claim 204 wherein the another interaction is an electrical connection to a surface of the device to which the substrate is physically connected, and which electrical connection does not pass through any portion of the substrate.

207. (previously presented) The cooling system according to claim 204 wherein the another interaction is one of pressure, sound, chemical, mechanical force, and an electromagnetic field.

208. (previously presented) The cooling system according to claim 204 wherein the opening is created by a surface area of the substrate that contacts a corresponding surface area of the device being smaller than the corresponding surface area of the device.

209. (previously presented) A thermal transfer apparatus connected to a semiconductor heat emitting device, the thermal transfer apparatus operating using a fluid having a liquid phase comprising:

a substrate adapted to physically connect to the semiconductor heat emitting device;

a plurality of fluid inlets disposed in the substrate;

a plurality of fluid outlets disposed in the substrate;

a plurality of microchannels connected between the plurality of fluid inlets and the plurality of fluid outlets, the plurality of microchannels thereby providing a plurality of independent fluid flow paths; and

wherein the arrangement of the microchannels is selected to minimize the temperature differences across the heat emitting device.

210. (canceled)

211. (previously presented) The apparatus according to claim 209 further including a plurality of temperature sensors respectively located in proximity to the plurality of microchannels, such that each of the temperature sensors detects thermal energy generated by the heat emitting device in proximity to said each temperature sensor.

212. (currently amended) The apparatus according to claim 211 further including a control circuit electrically connected to the plurality of temperature sensors, the control circuit

inputting signals from the plurality of temperature sensors and providing a control signal for controlling ~~the~~ a fluid pump.

213. (previously presented) The apparatus according to claim 212 further including a second fluid pump, such that the first fluid pump pumps the fluid through one microchannel and the second fluid pump pumps the fluid through another microchannel and wherein the control circuit controls the first and second fluid pumps, the control circuit being capable of independently controlling the pumping of fluid through each of the first and second fluid pumps.

214. (previously presented) The apparatus according to claim 209 further including:

a plurality of temperature sensors disposed within the substrate, such that a first temperature sensor detects thermal energy generated by the heat emitting device in proximity to the first temperature sensor and a second temperature sensor detects thermal energy generated by the heat emitting device in proximity to the second temperature sensor; and

a control circuit electrically connected to the first and second temperature sensors, the control circuit inputting signals from a first and second temperature sensors and providing a control signal for controlling the fluid pump.

215. (previously presented) The apparatus according to claim 214 wherein the control circuit operates to sense a predetermined condition.

216. (previously presented) The apparatus according to claim 215 wherein upon sensing the condition, the control circuit causes a reversal of the fluid flow for a period of time.

217. (previously presented) The apparatus according to claim 215 wherein the control circuit detects a change in temperature over a period of time and correspondingly adjusts the fluid flow within the fluid pump to compensate for the change in temperature.

218. (previously presented) The apparatus according to claim 209 further including a plurality of temperature sensors respectively located in proximity to the plurality of microchannels, such that each temperature sensor detects thermal energy generated by the heat emitting device in proximity to said each temperature sensor.

219. (previously presented) The apparatus according to claim 209 wherein each of the plurality of microchannels contain portions that are disposed parallel and adjacent to one another such that fluid flow in one microchannel occurs in a direction opposite the fluid flow in another microchannel.

220. (previously presented) The apparatus according to claim 209 wherein a first microchannel is at least partially disposed over a high thermal energy location of the heat emitting device and a second microchannel is disposed over another portion of the heat emitting device different from the high thermal energy location.

221. (previously presented) The cooling system according to claim 209 wherein the substrate further includes a plurality of vertical electrical interconnects.

222. (previously presented) The cooling system according to claim 221 wherein the plurality of vertical interconnects provide a portion of an electrical connection that electrically connects a plurality of temperature sensors to a temperature control circuit.

223. (previously presented) The cooling system according to claim 209 wherein the substrate includes an opening through which another interaction is capable of impinging upon a portion of the heat emitting device.

224. (previously presented) The cooling system according to claim 223 wherein the another interaction is an electrical interaction.

225. (previously presented) The cooling system according to claim 224 wherein the electrical interaction is an electrical connection to a surface of the device to which the substrate is physically connected, and which electrical connection does not pass through any portion of the substrate.

226. (previously presented) The cooling system according to claim 223 wherein the another interaction is one of pressure, sound, chemical, mechanical force, and an electromagnetic field.

227. (previously presented) The cooling system according to claim 223 wherein the opening is a vertical column having enclosed sidewalls.

228. (previously presented) The cooling system according to claim 209 wherein a portion of at least one of the plurality of microchannels includes:

an upper chamber;

a lower chamber; and

a plurality of subchannels disposed between the upper chamber and the lower chamber.

229. (canceled)